

HN58C1001 Series

Preliminary

T-46-13-27

1M (128K x 8-bit) EEPROM

■ DESCRIPTION

The Hitachi HN58C1001 is a 1-Megabit CMOS Electrically Erasable Programmable Read Only Memory (EEPROM) organized as 131,072 x 8-bits. The HN58C1001 is capable of in-system electrical Byte and Page reprogrammability.

The HN58C1001 achieves high speed access, low power consumption, and a high level of reliability by employing advanced MNOS memory technology and CMOS process and circuitry technology.

The HN58C1001 has a 128-Byte Page Programming function to make its erase and write operations faster. The HN58C1001 features Data Polling and a Ready/Busy signal to indicate completion of erase and programming operations.

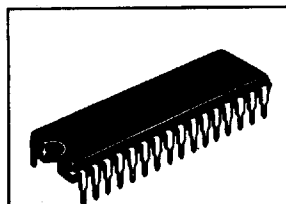
The HN58C1001 provides several levels of data protection. Hardware data protection is provided with the RES pin, in addition to noise protection on the WE signal and write inhibit on power on and off. Software data protection is implemented using the JEDEC Optional Standard algorithm.

The HN58C1001 is designed for high reliability in the most demanding applications. Data retention is specified for 10 years and erase/write endurance is guaranteed to a minimum of 100,000 cycles in the Page Mode.

The HN58C1001 is offered in 32-pin Plastic DIP and 32-lead Plastic SOP and TSOP packages. The HN58C1001 TSOP is offered in both standard and reverse bend pinouts.

■ FEATURES

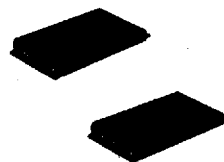
- Single Power Supply:
 $V_{cc} = 5V \pm 10\%$
- High Speed Access Times:
120 ns/150 ns (max)
- Low Power Dissipation:
Active Current: 20 mW/MHz (typ)
Standby Current: 100 μ W (max)
- Automatic Programming:
Automatic Page Write: 10 ms (max)
128 Byte Page Size
Automatic Byte Write: 10 ms (max)
- Data Polling and Ready/Busy Signals
- Hardware Data Protection with RES pin
- Data Protection Circuitry on Power On/Off
- Software Data Protection Algorithm
- Data Retention: 10 years
- Erase/Write Endurance:
100,000 cycles in Page Mode
- Packages:
32-pin Plastic DIP
32-pin Plastic SOP
32-lead Plastic TSOP (Type I)



(DP-32)



(FP-32D)



(TFP-32DA and TFP-32DAR)

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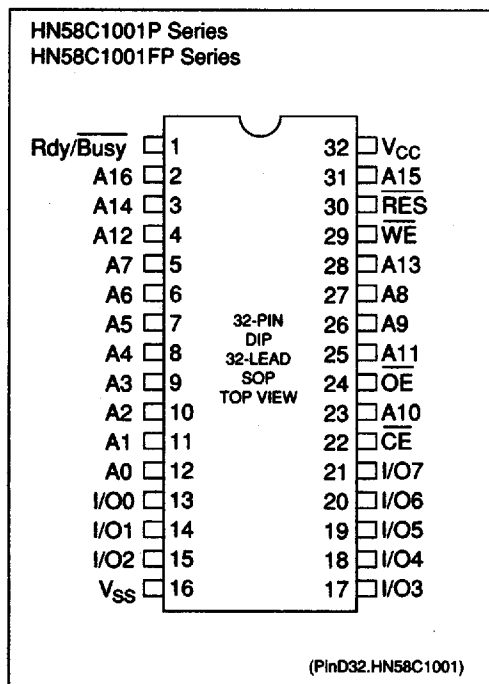
■ ORDERING INFORMATION

Type No.	Access Time	Package
HN58C1001P-12	120 ns	32-pin Plastic DIP
HN58C1001P-15	150 ns	(DP-32)
HN58C1001FP-12	120 ns	32-lead Plastic SOP
HN58C1001FP-15	150 ns	(FP-32D)
HN58C1001T-12	120 ns	32-lead Plastic TSOP
HN58C1001T-15	150 ns	(TFP-32DA)
HN58C1001R-12	120 ns	32-lead Plastic TSOP
HN58C1001R-15	150 ns	(TFP-32DAR)
		Reverse bend

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■ PIN ARRANGEMENT



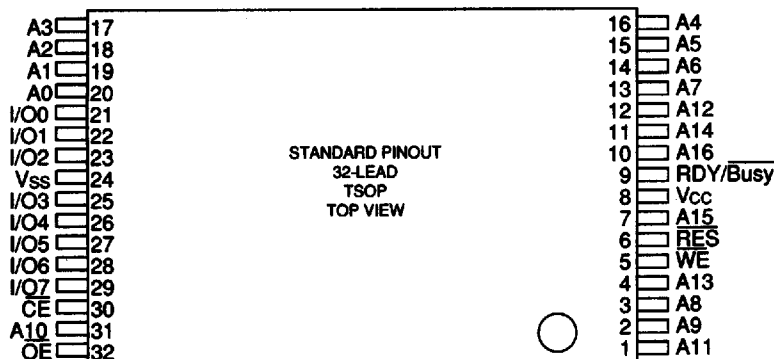
■ PIN DESCRIPTION

Pin Name	Function
$A_0 - A_{16}$	Address
$I/O_0 - I/O_7$	Input/Output
$\overline{OE}$	Output Enable
$\overline{CE}$	Chip Enable
$\overline{WE}$	Write Enable
V_{CC}	Power Supply
V_{SS}	Ground
Rdy/Busy	Ready/Busy
$\overline{RES}$	Reset

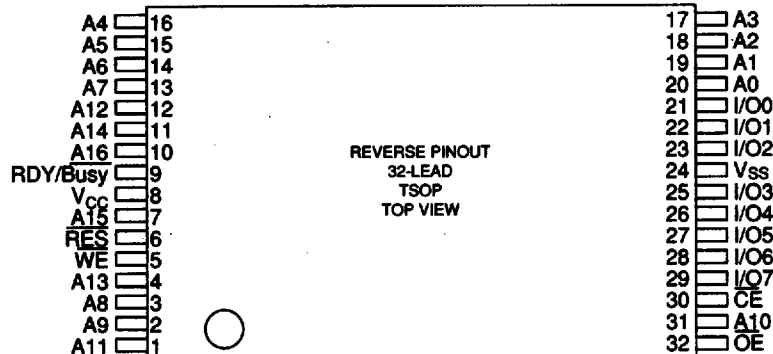
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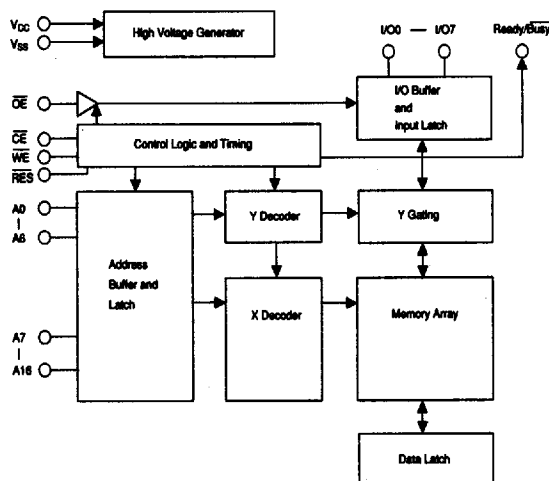
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■ PIN ARRANGEMENT (cont.)**HN58C1001T Series**

(PinT132.HN58C1001T)

HN58C1001R Series

(PinT132.HN58C1001R)

■ BLOCK DIAGRAM

(BD.HN58C1001)

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■ MODE SELECTION

Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{RES}$	RDY/Busy	I/O
Read	V_{IL}	V_{IL}	V_{IH}	V_H	High-Z	D_{OUT}
Standby	V_{IH}	X	X	X	High-Z	High-Z
Write	V_{IL}	V_{IH}	V_{IL}	V_H	High-Z $\rightarrow$ V_{OL}	Din
Deselect	V_{IL}	V_{IH}	V_{IH}	V_H	High-Z	High-Z
Write Inhibit	X	X	V_{IH}	X	-	-
	X	V_{IL}	X	X	-	-
Data Polling	V_{IL}	V_{IL}	V_{IH}	V_H	V_{OL}	Data Out (I/O ₂)
Program	X	X	X	V_{IL}	High-Z	High-Z

Note: 1. X = Don't Care

■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage ¹	V_{CC}	-0.6 to +7.0	V
Input Voltage ¹	V_{IN}	-0.5 ² to +7.0	V
Operating Temperature Range ³	T_{OPR}	0 to +70	°C
Storage Temperature Range	T_{STG}	-55 to +125	°C

Notes: 1. Relative to V_{SS} .2. V_{IN} min = -3.0V for pulse width $\leq$ 50 ns.■ CAPACITANCE ($T_a = 25^\circ\text{C}$, $f = 1\text{MHz}$)

Item	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Input Capacitance	C_{IN}	-	-	6	pF	$V_{IN} = 0V$
Output Capacitance	C_{OUT}	-	-	12	pF	$V_{OUT} = 0V$

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■ DC ELECTRICAL CHARACTERISTICS

(V_{CC} = 5V ± 10%, T_a = 0 to 70°C)

Item	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Input Leakage Current	I _{LI}	-	-	2	μA	V _{CC} = 5.5 V, V _{IN} = 5.5 V
Output Leakage Current	I _{LO}	-	-	2	μA	V _{CC} = 5.5 V, V _{OUT} = 5.5 V/0.4 V
Standby V _{CC} Current	I _{CC1}	-	-	20	μA	$\overline{CE} = V_{CC}$
	I _{CC2}	-	-	1	mA	$\overline{CE} = V_{IH}$
Operating V _{CC} Current	I _{CC3}	-	-	15	mA	I _{OUT} = 0 mA, Duty = 100%, Cycle = 1 μs
		-	-	40	mA	I _{OUT} = 0 mA, Duty = 100%, Cycle = 200 ns
Input Voltage	V _{IL}	-0.3 ¹	-	0.8	V	
	V _{IH}	2.2	-	V _{CC} + 1	V	
	V _H	V _{CC} - 1.0	-	V _{CC} + 1	V	
Output Voltage	V _{OL}	-	-	0.4	V	I _{OL} = 2.1 mA
	V _{OH}	2.4	-	-	V	I _{OH} = -400 μA

- Notes: 1. V_{IL} min = -1.0 V for pulse width ≤ 50 ns.
2. I_{LI} on RES = 100 μA Max.

■ AC ELECTRICAL CHARACTERISTICS FOR READ OPERATION

(T_a = 0 to 70°C, V_{CC} = 5V ± 10%)

Test Conditions

- Input pulse levels: 0.4 V to 2.4 V
- Input rise and fall times: ≤ 20 ns
- Output load: 1 TTL Gate + 100 pF (Including scope and jig)
- Reference levels for measuring timing: 0.8 V, 1.8 V

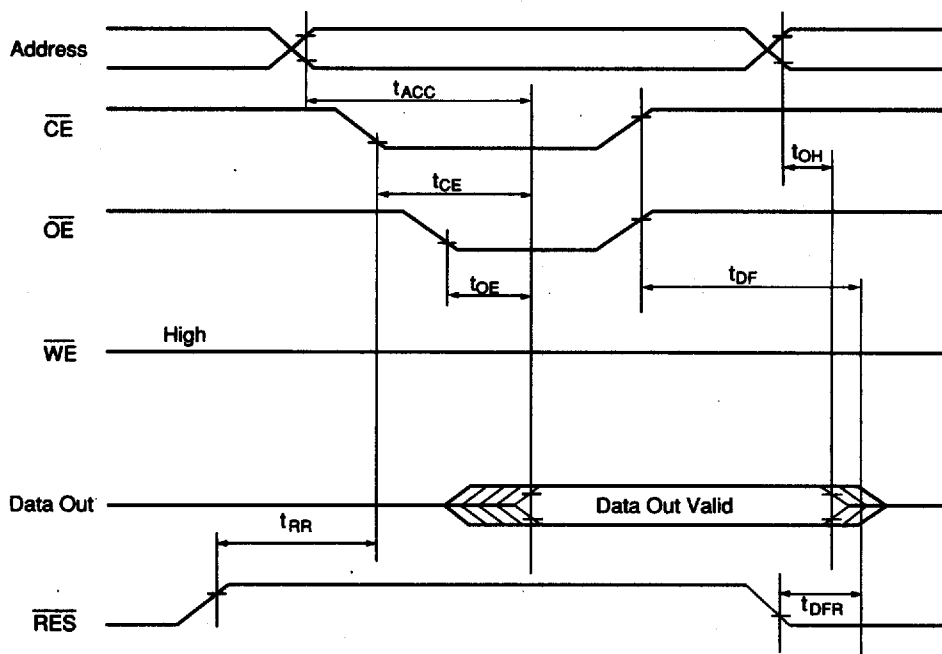
Item	Symbol	HN58C1001-12		HN58C1001-15		Unit	Test Condition
		Min.	Max.	Min.	Max.		
Address Access Time	t _{ACC}	-	120	-	150	ns	$\overline{CE} = \overline{OE} = V_{IL}, \overline{WE} = V_{IH}$
Chip Enable Access Time	t _{CE}	-	120	-	150	ns	$\overline{OE} = V_{IL}, \overline{WE} = V_{IH}$
Output Enable Access Time	t _{OE}	10	60	10	75	ns	$\overline{CE} = V_{IL}, \overline{WE} = V_{IH}$
Output Hold to Address Change	t _{OH}	0	-	0	-	ns	$\overline{CE} = \overline{OE} = V_{IL}, \overline{WE} = V_{IH}$
Output Disable to High-Z ¹	t _{DF}	0	45	0	50	ns	$\overline{CE} = V_{IL}, \overline{WE} = V_{IH}$
	t _{DFR}	0	350	0	350	ns	$\overline{CE} = \overline{OE} = V_{IL}, \overline{WE} = V_{IH}$
RES to Output Delay	t _{RR}	0	450	0	450	ns	$\overline{CE} = \overline{OE} = V_{IL}, \overline{WE} = V_{IH}$

Note: 1. t_{DF} is defined as the time at which the output becomes an open circuit and data is no longer driven.

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■ READ TIMING WAVEFORM

T-46-13-27



(TD.R.HN58C1001)

■ AC ELECTRICAL CHARACTERISTICS FOR BYTE ERASE AND BYTE WRITE OPERATIONS

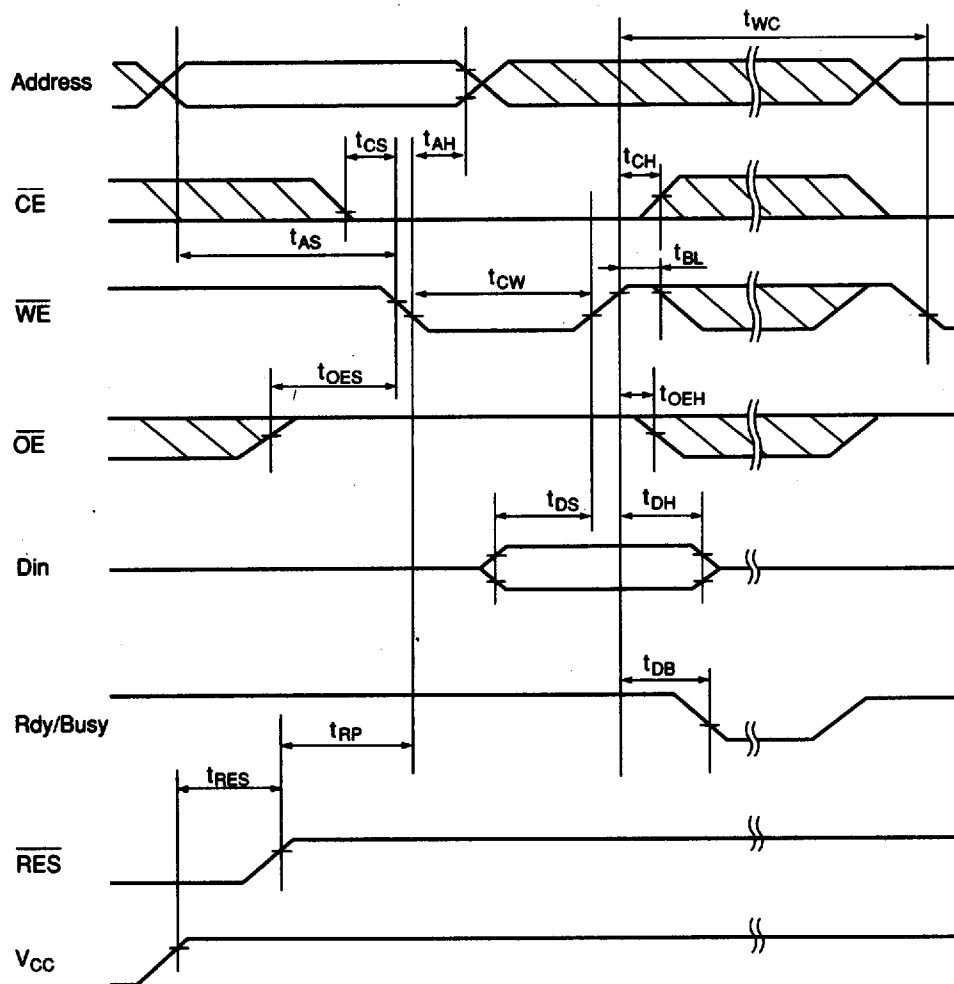
Item	Symbol	Min. ¹	Typ.	Max.	Unit	Test Condition
Address Setup Time	t_{AS}	0	-	-	ns	
Chip Enable to Write Setup Time	t_{CS}	0	-	-	ns	
Write Pulse Width	t_{CW}	150	-	-	ns	
Address Hold Time	t_{AH}	150	-	-	ns	
Data Setup Time	t_{DS}	100	-	-	ns	
Data Hold Time	t_{DH}	0	-	-	ns	
Chip Enable Hold Time	t_{CH}	0	-	-	ns	
Output Enable to Write Setup Time	t_{OES}	0	-	-	ns	
Output Enable Hold Time	t_{OEH}	0	-	-	ns	
Write Cycle Time	t_{WC}	10	-	-	ms	
Byte Load Window	t_{BL}	100	-	-	μ s	
Time to Device Busy	t_{DB}	120	-	-	ns	
$\overline{RES}$ to Write Setup Time	t_{RP}	100	-	-	μ s	
V_{CC} to $\overline{RES}$ Setup Time	t_{RES}	1	-	-	μ s	

Note: 1. Use this device in a longer cycle than this value.

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HN58C1001 Series**■ BYTE ERASE AND BYTE WRITE TIMING WAVEFORM ($\overline{\text{WE}}$ Controlled)**

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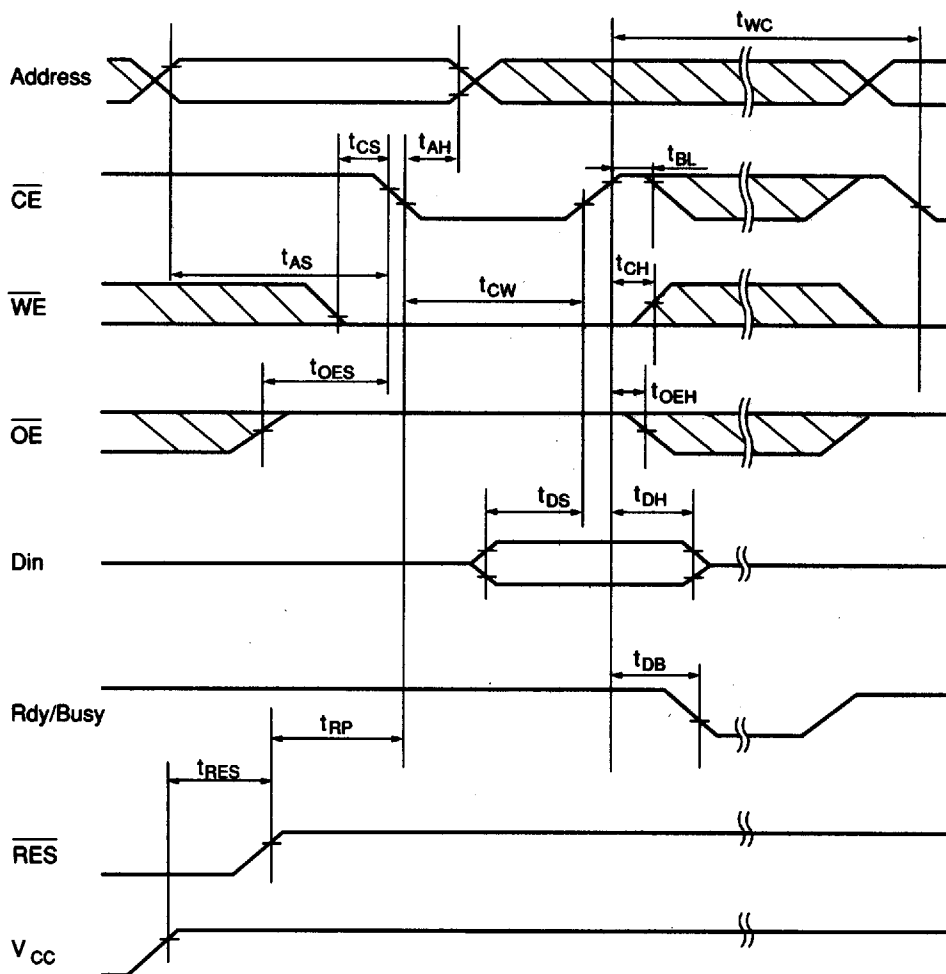


(TD.BE1.HN58C1001)

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■ BYTE ERASE AND BYTE WRITE TIMING WAVEFORM ($\overline{\text{CE}}$ Controlled)

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(TD.BE2.HN58C1001)

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HN58C1001 Series

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■ AC ELECTRICAL CHARACTERISTICS FOR PAGE ERASE AND PAGE WRITE OPERATIONS

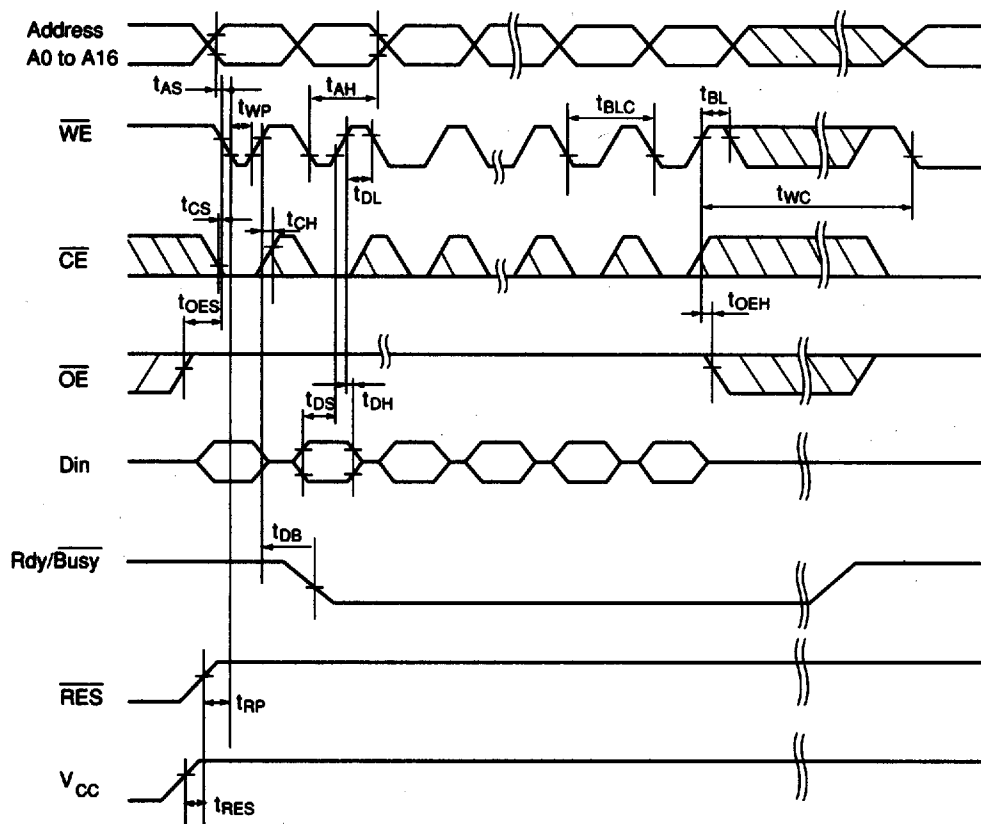
Item	Symbol	Min. ¹	Typ.	Max.	Unit	Test Condition
Address Setup Time	t_{AS}	0	-	-	ns	
Chip Enable to Write Setup Time	t_{CS}	0	-	-	ns	
Write Pulse Width	t_{WP}^2	150	-	-	ns	
	t_{CW}^3	150	-	-	ns	
Address Hold Time	t_{AH}	150	-	-	ns	
Data Setup Time	t_{DS}	100	-	-	ns	
Data Hold Time	t_{DH}	0	-	-	ns	
Chip Enable Hold Time	t_{CH}	0	-	-	ns	
Output Enable to Write Setup Time	t_{OES}	0	-	-	ns	
Output Enable Hold Time	t_{OEH}	0	-	-	ns	
Data Latch Time	t_{DL}	200	-	-	ns	
Write Cycle Time	t_{WC}	10	-	-	ms	
Byte Load Window	t_{BL}	100	-	-	μ s	
Byte Load Cycle	t_{BLC}	0.35	-	30	μ s	
Time to Device Busy	t_{DB}	120	-	-	ns	
$\overline{RES}$ to Write Setup Time	t_{RP}	100	-	-	μ s	
V_{CC} to $\overline{RES}$ Setup Time	t_{RES}	1	-	-	μ s	

- Notes:
1. Use this device in longer cycle than this value.
 2. $\overline{WE}$ controlled operation.
 3. $\overline{CE}$ controlled operation.

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■ PAGE ERASE AND PAGE WRITE TIMING WAVEFORM ($\overline{WE}$ Controlled)

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(TD, PE1, HN58C1001)

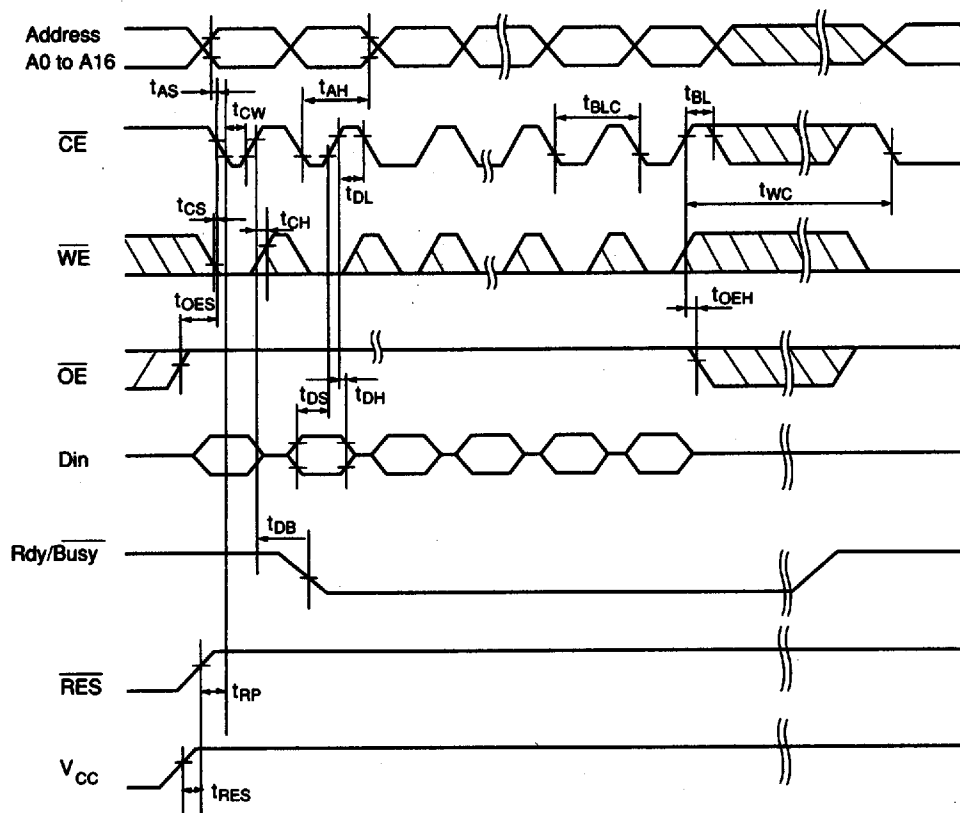
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■ PAGE ERASE AND PAGE WRITE TIMING WAVEFORM ($\overline{CE}$ Controlled)

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(TD.PE2.HN58C1001)

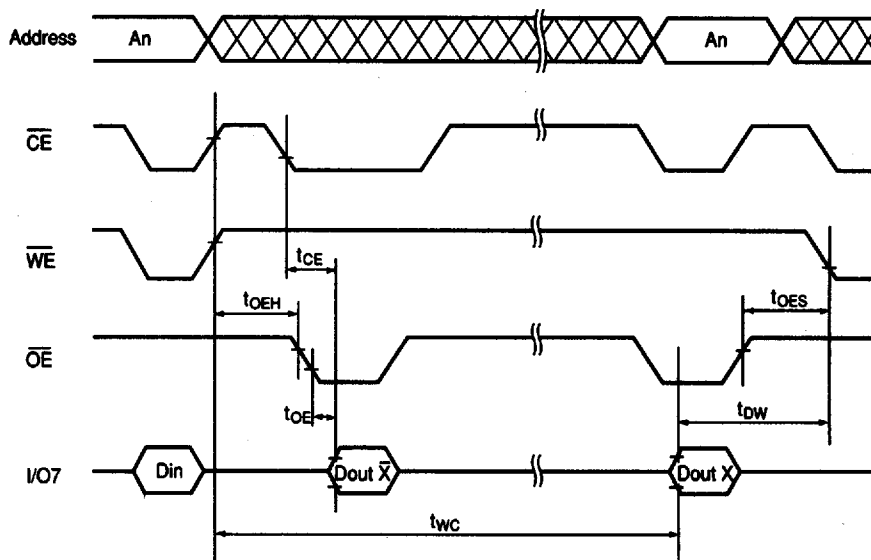
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■ AC ELECTRICAL CHARACTERISTICS FOR DATA POLLING OPERATION

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Item	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Output Enable Hold Time	t_{OEH}	0	-	-	ns	
Output Enable to Write Setup Time	t_{OES}	0	-	-	ns	
Write Start Time	t_{DW}	150	-	-	ns	
Write Cycle Time	t_{WC}	-	-	10	ms	

■ DATA POLLING TIMING WAVEFORM



(TD.DP.HN58C1001)

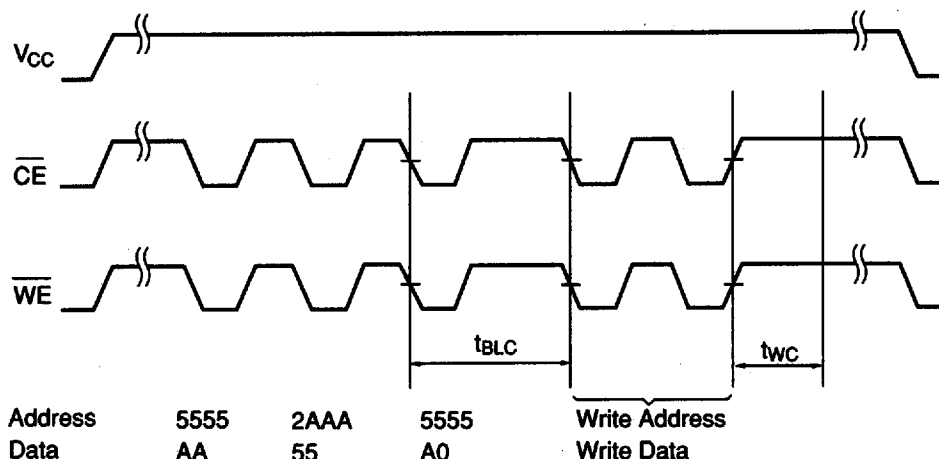
■ AC ELECTRICAL CHARACTERISTICS FOR SOFTWARE DATA PROTECTION CYCLE OPERATION

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HITACHI/ LOGIC/ARRAYS/MEM

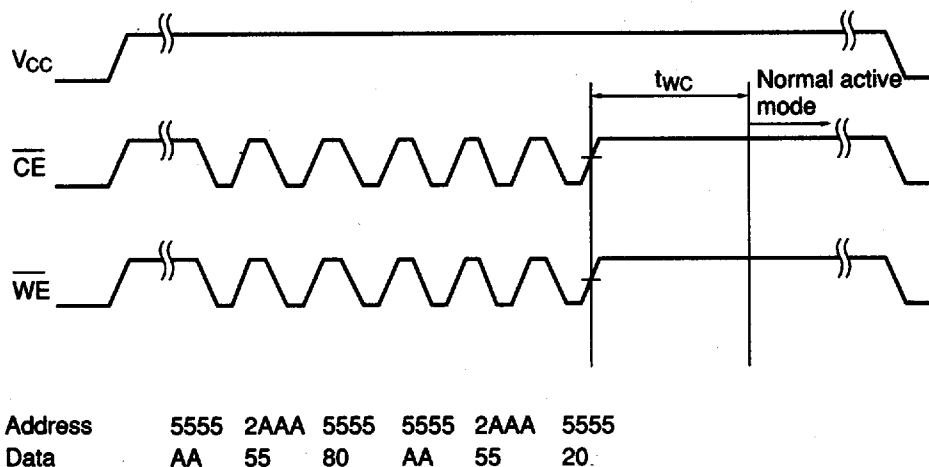
Item	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Byte Load Cycle Time	t_{BLC}	0.35	-	30	μs	
Write Cycle Time	t_{WC}	10	-	-	ms	

■ SOFTWARE DATA PROTECTION TIMING WAVEFORM (Protection Mode)



(TD.SD1.HN58C1001)

■ SOFTWARE DATA PROTECTION TIMING WAVEFORM (Non-Protection Mode)



(TD.SD2.HN58C1001)

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T-46-13-27

■ **DEVICE IDENTIFIER MODE DESCRIPTION**

The Device Identifier Mode allows binary codes to be read from the outputs that identify the manufacturer and the type of device. Using this mode with programming equipment, the device will automatically match its own erase and programming algorithm.

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■ **HN58C1001 SERIES IDENTIFIER CODE**

Identifier	A ₀	I/O ₇	I/O ₆	I/O ₅	I/O ₄	I/O ₃	I/O ₂	I/O ₁	I/O ₀	Hex Data
Manufacturer Code	V _{IL}	0	0	0	0	0	1	1	1	07
Device Code	V _{IH}	0	1	0	1	1	0	0	0	58

- Notes:
1. $V_{CC} = 5.0\text{ V} \pm 10\%$
 2. $A_9 = 12.0\text{ V} \pm 0.5\text{ V}$
 3. $A_1-A_9, A_{10}-A_{18}, \overline{CE}, \overline{OE} = V_{IL}, \overline{WE} = V_{IH}$

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■ FUNCTIONAL DESCRIPTION

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Automatic Page Write

The Page Write feature allows 1 to 128 Bytes of data to be written into the EEPROM in a single cycle and allows the undefined data within 128 Bytes to be written corresponding to the undefined address (A_0 to A_6). Loading the first Byte of data, the data load window of 30 μ s opens for the second. In the same manner each additional Byte of data can be loaded within 30 μ s. In case $\overline{CE}$ and $\overline{WE}$ are kept high for 100 μ s after data input, the EEPROM enters erase and write automatically and only the input data are written into the EEPROM. In Page mode the data can be written and accessed 10^5 times per page, and in Byte mode 10^4 times per Byte.

Data Polling

Data Polling allows the status of the EEPROM to be determined. If the EEPROM is set to Read mode during a Write cycle, an inversion of the last Byte of data to be loaded outputs from I/O_7 to indicate that the EEPROM is performing a Write operation.

Write Protection

- (1) Noise protection: Noise on a write cycle will not act as a trigger with a $\overline{WE}$ pulse of less than 20 ns.
- (2) Write inhibit: Holding $\overline{OE}$ low, $\overline{WE}$ high, or $\overline{CE}$ high, inhibits a write cycle during power on/off.

 $\overline{WE}$ and $\overline{CE}$ Pin Operation

During a write cycle, addresses are latched by the falling edge of $\overline{WE}$ or $\overline{CE}$, and data is latched by the rising edge of $\overline{WE}$ or $\overline{CE}$.

Write/Erase Endurance and Data Retention

The endurance with page programming is 10^5 cycles (1% cumulative failure rate) and the data retention time is more than 10 years when a device is programmed less than 10^4 cycles.

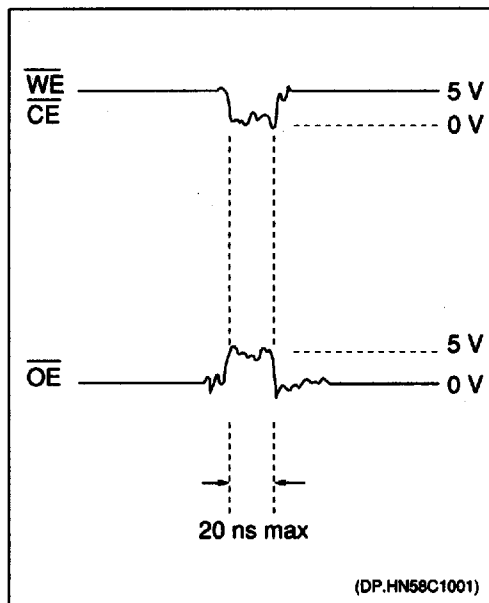
Data Protection

T-46-13-27

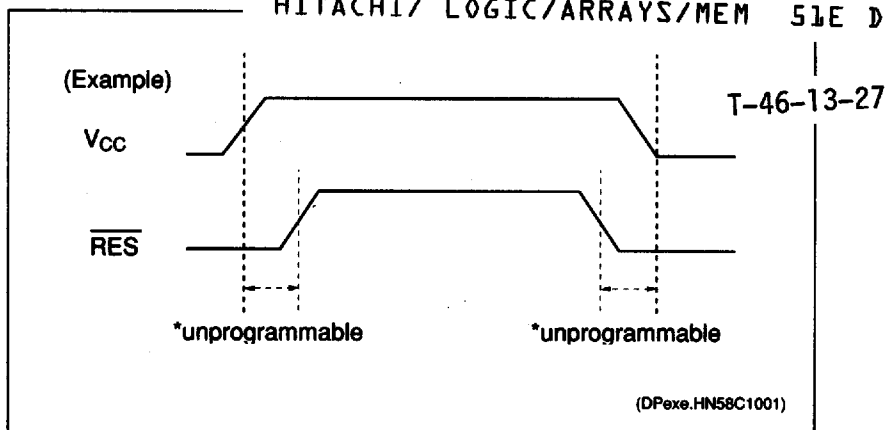
To protect the data during operation and power on/off, the HN58C1001 has:

1. Data protection against Noise on Control Pins ($\overline{CE}$, $\overline{OE}$, $\overline{WE}$) during Operation.

During readout or standby, noise on the control pins may act as a trigger and turn the EEPROM to programming mode by mistake. To prevent this phenomenon, the HN58C1001 has a noise cancellation function that cuts noise if its width is 20 ns or less in programming mode. Be careful not to allow noise of a width of more than 20 ns on the control pins.



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FUNCTIONAL DESCRIPTION (continued)

Data Protection (continued)

2. Data protection at V_{CC} on/off

When RES is low, the EEPROM cannot be erased and programmed. Therefore, data can be protected by keeping RES low when V_{CC} is switched. RES should be high during programming because it does not provide a latch function.

When V_{CC} is turned on or off, noise on the control pins generated by external circuits (CPU, etc) may turn the EEPROM to programming mode by mistake. To prevent this unintentional programming, the EEPROM must be kept in an unprogrammable, standby or readout state by using a CPU reset signal to RES pin.

In addition, when RES is kept high at V_{CC} on/off timing, the input level of control pins ($\overline{CE}$, $\overline{OE}$, $\overline{WE}$) must be held as $\overline{CE}=V_{CC}$ or $\overline{OE}=\text{Low}$ or $\overline{WE}=V_{CC}$ level.

3. Software data protection

To prevent unintentional programming caused by noise generated by external circuits, HN58C1001 has a Software data protection function. In Software data protection mode, 3 Bytes of data must be input before the Write data. These Bytes can switch the Non-Protection mode to the Protection mode.

Address	Data
5555	AA
↓	↓
2AAA	55
↓	↓
5555	A0
↓	↓

Write Address Write Data (Normal Data Input)

The Software data protection mode can be cancelled by inputting the following 6 Bytes. This changes the HN58C1001 turns to the Non-Protection mode and it can write data normally. When the data is input during the cancelling cycle, the data cannot be written.

Address	Data
5555	AA
↓	↓
2AAA	55
↓	↓
5555	80
↓	↓
5555	AA
↓	↓
2AAA	55
↓	↓
5555	20

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